



High-end Power Semiconductor Manufacturer

KP1600A 5400V-6500V Phase Control Thyristor

- High power cycling capability
- Low on-state and switching losses
- Designed for traction and industrial applications



Mean on-state current		I _{TAV}	1600 A				
Repetitive peak off-state voltage		V _{DRM}	5400 – 6500 V				
Repetitive peak reverse voltage		V _{RRM}					
Turn-off time		t _q	800 μs				
V _{DRM} , V _{RRM} , V	5400	5600	5800	6000	6200	6400	6500
Voltage code	54	56	58	60	62	64	65
T _j , °C	– 60 – 125						

MAXIMUM ALLOWABLE RATINGS

Symbols and parameters		Units	Values	Test conditions	
ON-STATE					
I _{TAV}	Mean on-state current	A	1600	T _c = 85 °C, Double side cooled 180° half-sine wave; 50 Hz	
I _{TRMS}	RMS on-state current	A	2512	T _c = 85 °C, Double side cooled 180° half-sine wave; 50 Hz	
I _{TSM}	Surge on-state current	kA	40.0	T _j =T _j max T _j =25 °C	180° half-sine wave; 50 Hz (t _p =10 ms); single pulse; V _D =V _R =0 V; Gate pulse: I _G =2 A; t _{GP} =50 μs; di _G /dt≥1 A/μs
			46.0	T _j =T _j max T _j =25 °C	180° half-sine wave; 60 Hz (t _p =8.3 ms); single pulse; V _D =V _R =0 V; Gate pulse: I _G =2 A; t _{GP} =50 μs; di _G /dt≥1 A/μs
I ² t	Safety factor	A ² s·10 ³	42.0	T _j =T _j max T _j =25 °C	180° half-sine wave; 50 Hz (t _p =10 ms); single pulse; V _D =V _R =0 V; Gate pulse: I _G =2 A; t _{GP} =50 μs; di _G /dt≥1 A/μs
			48.0	T _j =T _j max T _j =25 °C	180° half-sine wave; 60 Hz (t _p =8.3 ms); single pulse; V _D =V _R =0 V; Gate pulse: I _G =2 A; t _{GP} =50 μs; di _G /dt≥1 A/μs

BLOCKING

V _{DRM} , V _{RRM}	Repetitive peak off-state and Repetitive peak reverse voltages	V	5400–6500	T _{j min} < T _j <T _{j max} 180° half-sine wave; 50 Hz; Gate open
V _{DSM} , V _{RSM}	Non-repetitive peak off-state and Non-repetitive peak reverse voltages	V	5500–6600	T _{j min} < T _j <T _{j max} 180° half-sine wave; 50 Hz;single pulse; Gate open
V _D , V _R	Direct off-state and Direct reverse voltages	V	0.75V _{DRM} 0.75V _{RRM}	T _j =T _j max; Gate open

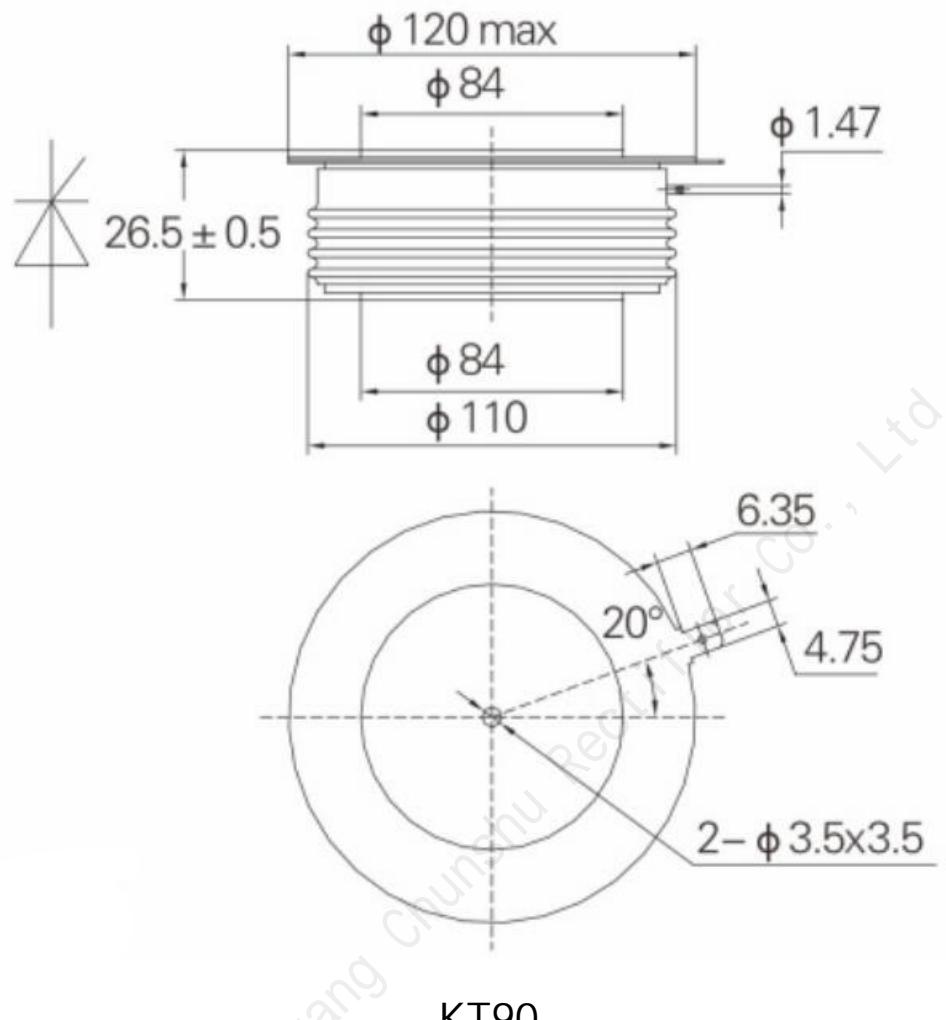
TRIGGERING				
I_{FGM}	Peak forward gate current	A	10	$T_j = T_{j \max}$
V_{RGM}	Peak reverse gate voltage	V	5	
P_G	Gate power dissipation	W	5	$T_j = T_{j \max}$ for DC gate current
SWITCHING				
$(di_T/dt)_{crit}$	Critical rate of rise of on-state current non-repetitive ($f=1$ Hz)	A/ μ s	630	$T_j = T_{j \max}; V_D = 0.67 \cdot V_{DRM}; I_{TM} = 2 I_{TAV};$ Gate pulse: $I_G = 2$ A; $t_{GP} = 50 \mu$ s; $di_G/dt \geq 1$ A/ μ s
THERMAL				
T_{stg}	Storage temperature	°C	-60 – 125	
T_j	Operating junction temperature	°C	-60 – 125	
MECHANICAL				
F	Mounting force	kN	60.0 – 70.0	
a	Acceleration	m/s ²	50 100	Device unclamped Device clamped

CHARACTERISTICS

Symbols and parameters		Units	Values	Conditions		
ON-STATE						
V_{TM}	Peak on-state voltage, max	V	2.80	$T_j = 25$ °C; $I_{TM} = 6300$ A		
$V_{T(TO)}$	On-state threshold voltage, max	V	1.10	$T_j = T_{j \max};$		
r_T	On-state slope resistance, max	$m\Omega$	0.350	$0.5 \pi I_{TAV} < I_T < 1.5 \pi I_{TAV}$		
I_L	Latching current, max	mA	1500	$T_j = 25$ °C; $V_D = 12$ V; Gate pulse: $I_G = 2$ A; $t_{GP} = 50 \mu$ s; $di_G/dt \geq 1$ A/ μ s		
I_H	Holding current, max	mA	300	$T_j = 25$ °C; $V_D = 12$ V; Gate open		
BLOCKING						
I_{DRM}, I_{RRM}	Repetitive peak off-state and Repetitive peak reverse currents, max	mA	200	$T_j = T_{j \max};$ $V_D = V_{DRM}; V_R = V_{RRM}$		
$(dv_D/dt)_{crit}$	Critical rate of rise of off-state voltage ¹⁾ , min	V/ μ s	1000	$T_j = T_{j \max};$ $V_D = 0.67 \cdot V_{DRM};$ Gate open		
TRIGGERING						
V_{GT}	Gate trigger direct voltage, max	V	3.00 2.00	$T_j = 25$ °C $T_j = T_{j \max}$	$V_D = 12$ V; $I_D = 3$ A; Direct gate current	
I_{GT}	Gate trigger direct current, max	mA	300 200	$T_j = 25$ °C $T_j = T_{j \max}$		
V_{GD}	Gate non-trigger direct voltage, min	V	0.35	$T_j = T_{j \max};$ $V_D = 0.67 \cdot V_{DRM};$		
I_{GD}	Gate non-trigger direct current, min	mA	15.00	Direct gate current		
SWITCHING						
t_{gd}	Delay time	μ s	4.00	$T_j = 25$ °C; $V_D = 0.4 \cdot V_{DRM}; I_{TM} = I_{TAV};$ Gate pulse: $I_G = 2$ A; $t_{GP} = 50 \mu$ s; $di_G/dt \geq 1$ A/ μ s		
t_q	Turn-off time ²⁾ , max	μ s	800	$dv_D/dt = 50$ V/ μ s; $T_j = T_{j \max}; I_{TM} = 2000$ A; $di_R/dt = -10$ A/ μ s; $V_R = 100$ V; $V_D = 0.67 \cdot V_{DRM}$		
Q_{rr}	Total recovered charge, max	μ C	7600	$T_j = T_{j \max}; I_{TM} = 2000$ A;		
t_{rr}	Reverse recovery time, typ	μ s	80	$di_R/dt = -5$ A/ μ s;		
I_{rrM}	Peak reverse recovery current, max	A	190	$V_R = 100$ V		

THERMAL					
R_{thjc}	Thermal resistance, junction to case, max	$^{\circ}\text{C}/\text{W}$	0.0065	Direct current	Double side cooled
R_{thjc-A}			0.0143		Anode side cooled
R_{thjc-K}			0.0117		Cathode side cooled
R_{thck}	Thermal resistance, case to heatsink, max	$^{\circ}\text{C}/\text{W}$	0.0015	Direct current	
MECHANICAL					
W	Weight, typ	g	1900		
D_s	Surface creepage distance	mm (inch)	36.50 (1.437)		
D_a	Air strike distance	mm (inch)	16.5 (0.650)		

OVERALL DIMENSIONS



All dimensions in millimeters

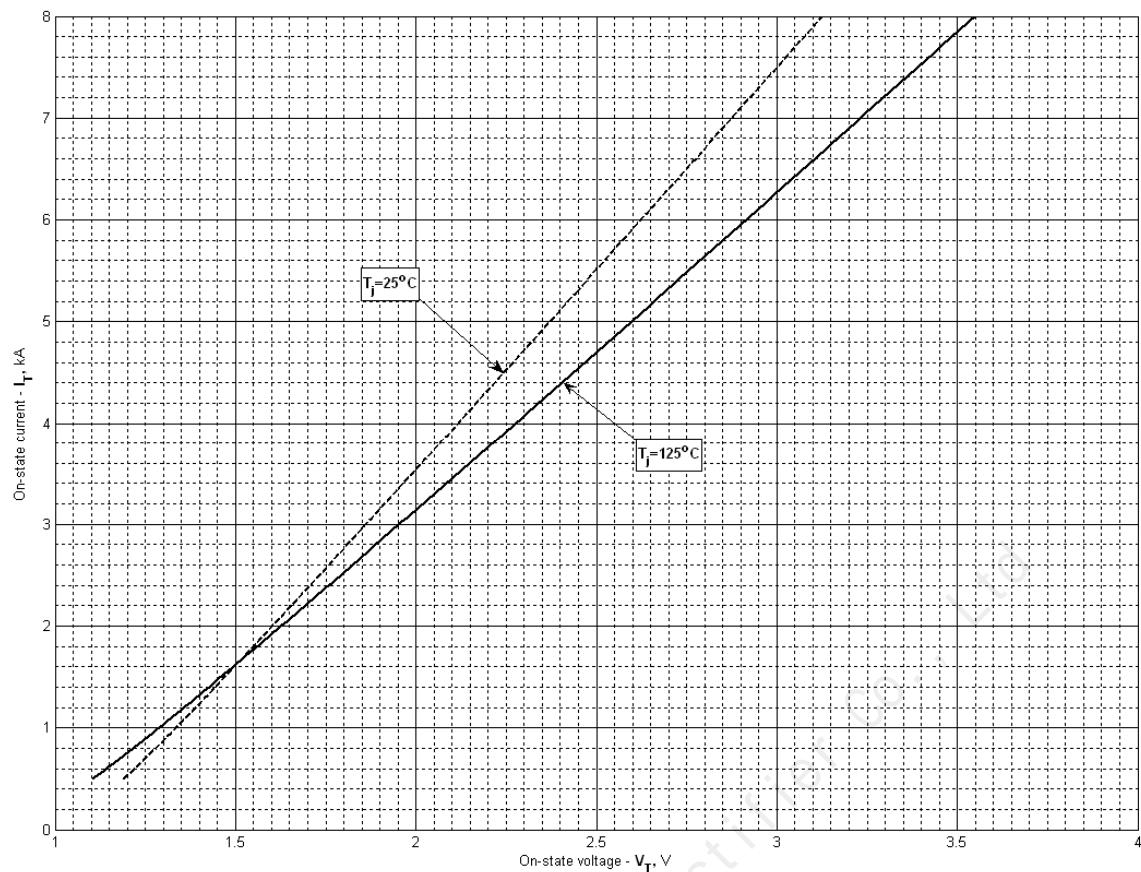


Fig 1 – On-state characteristics of Limit device

Analytical function for On-state characteristic:

$$V_T = A + B \cdot i_T + C \cdot \ln(i_T + 1) + D \cdot \sqrt{i_T}$$

	Coefficients for max curves	
	$T_j = 25^\circ\text{C}$	$T_j = T_{j \text{ max}}$
A	0.913434	0.744654
B	0.208728	0.259885
C	-0.253813	-0.338985
D	0.388412	0.518752

On-state characteristic model (see Fig. 1)

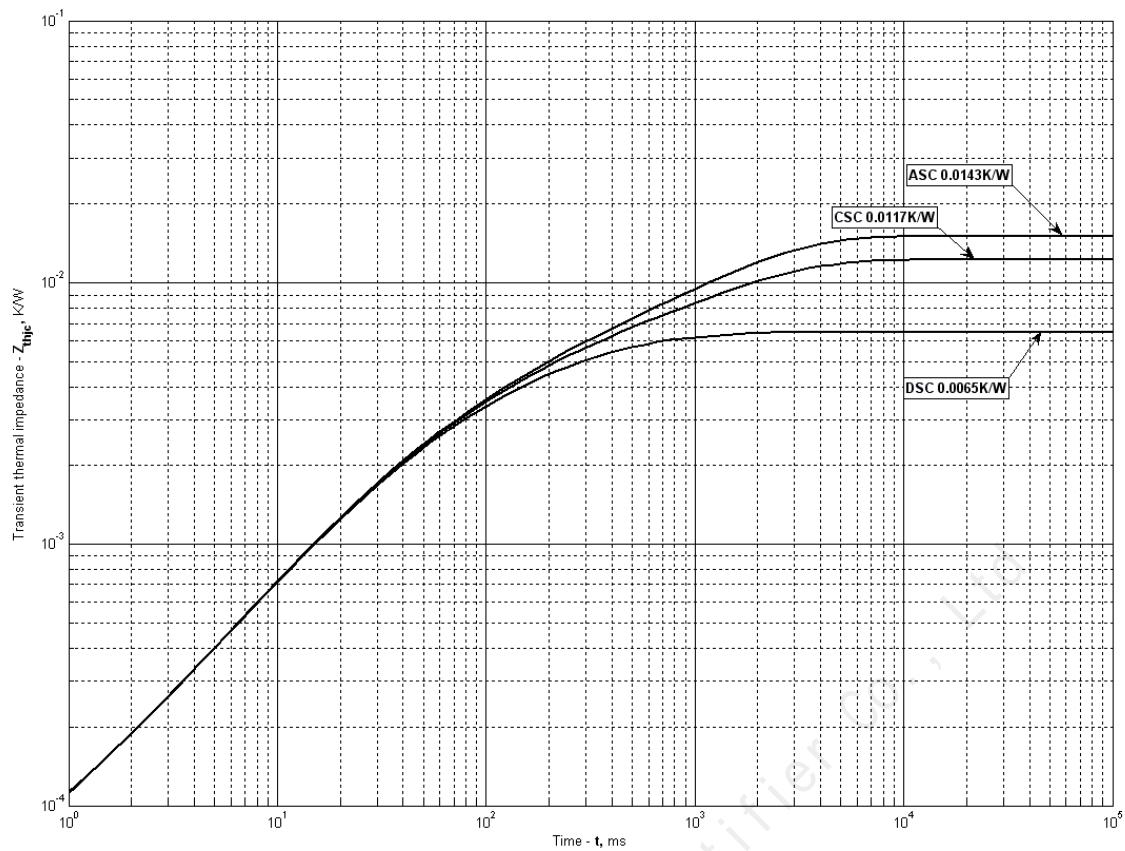


Fig 2 – Transient thermal impedance

Analytical function for Transient thermal impedance junction to case Z_{thjc} for DC:

$$Z_{thjc} = \sum_{i=1}^n R_i \left(1 - e^{-\frac{t}{\tau_i}} \right)$$

Where $i = 1$ to n , n is the number of terms in the series.

t = Duration of heating pulse in seconds.

Z_{thjc} = Thermal resistance at time t.

R_i = Amplitude of p_{th} term.

τ_i = Time constant of r_{th} term.

DC Double side cooled

i	1	2	3	4	5	6
R_i , K/W	0.001031	0.003117	0.001895	0.0004176	2.061e-005	1.999e-005
τ_i , s	0.7345	0.209	0.05291	0.01652	0.0006764	0.0002168

DC Cathode side cooled

i	1	2	3	4	5	6
R_i , K/W	0.001475	0.005797	0.002722	0.001822	0.0003923	3.824e-005
τ_i , s	0.8755	1.835	0.1997	0.05221	0.01594	0.0003499

DC Anode side cooled

i	1	2	3	4	5	6
R_i , K/W	0.00848	0.001792	0.002597	0.00179	0.0003904	3.851e-005
τ_i , s	1.845	0.9581	0.2011	0.05234	0.01605	0.0003606

Transient thermal impedance junction to case Z_{thjc} model (see Fig. 2)

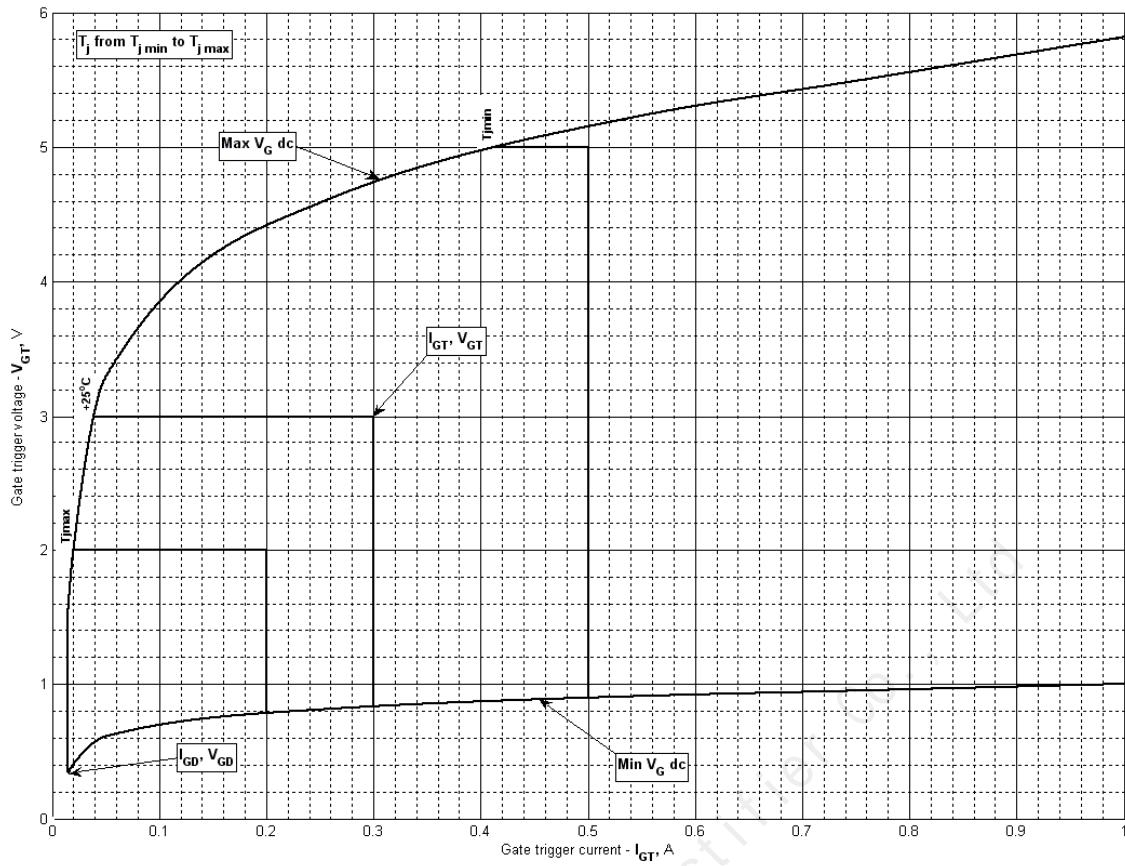


Fig 3 – Gate characteristics – Trigger limits

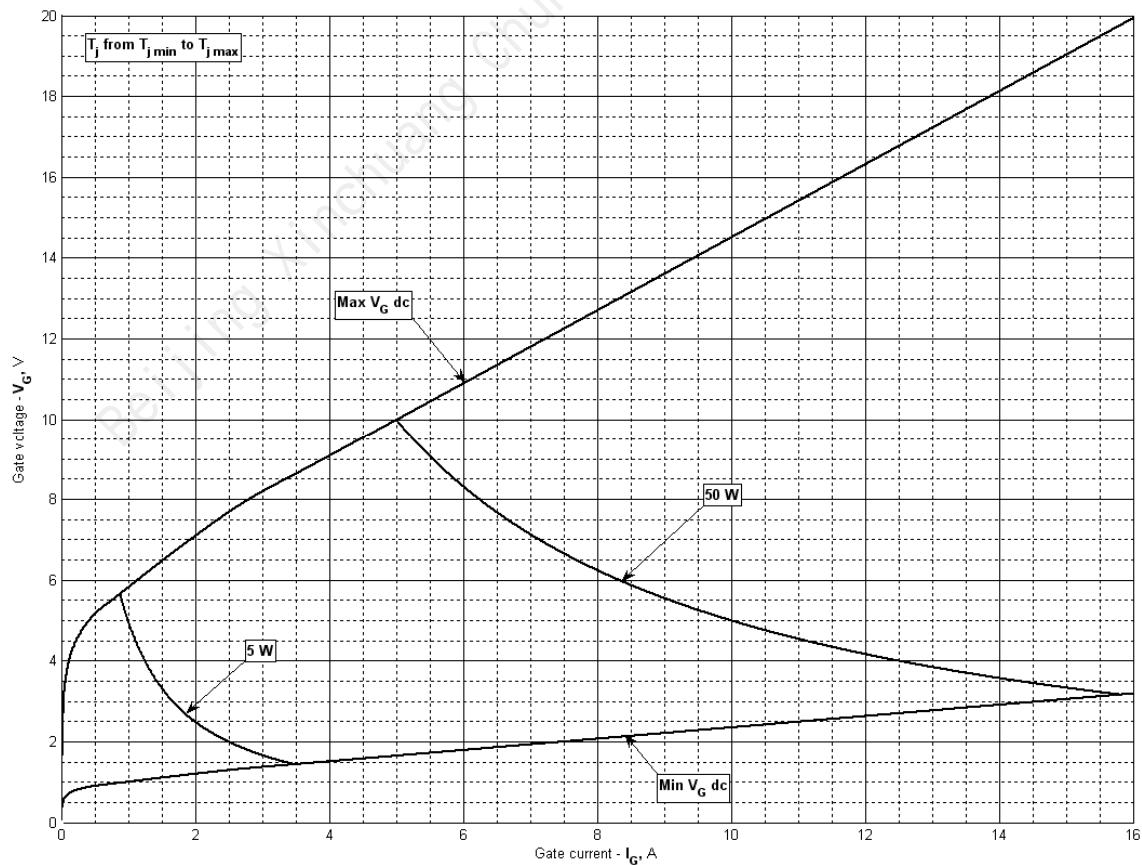


Fig 4 - Gate characteristics –Power curves

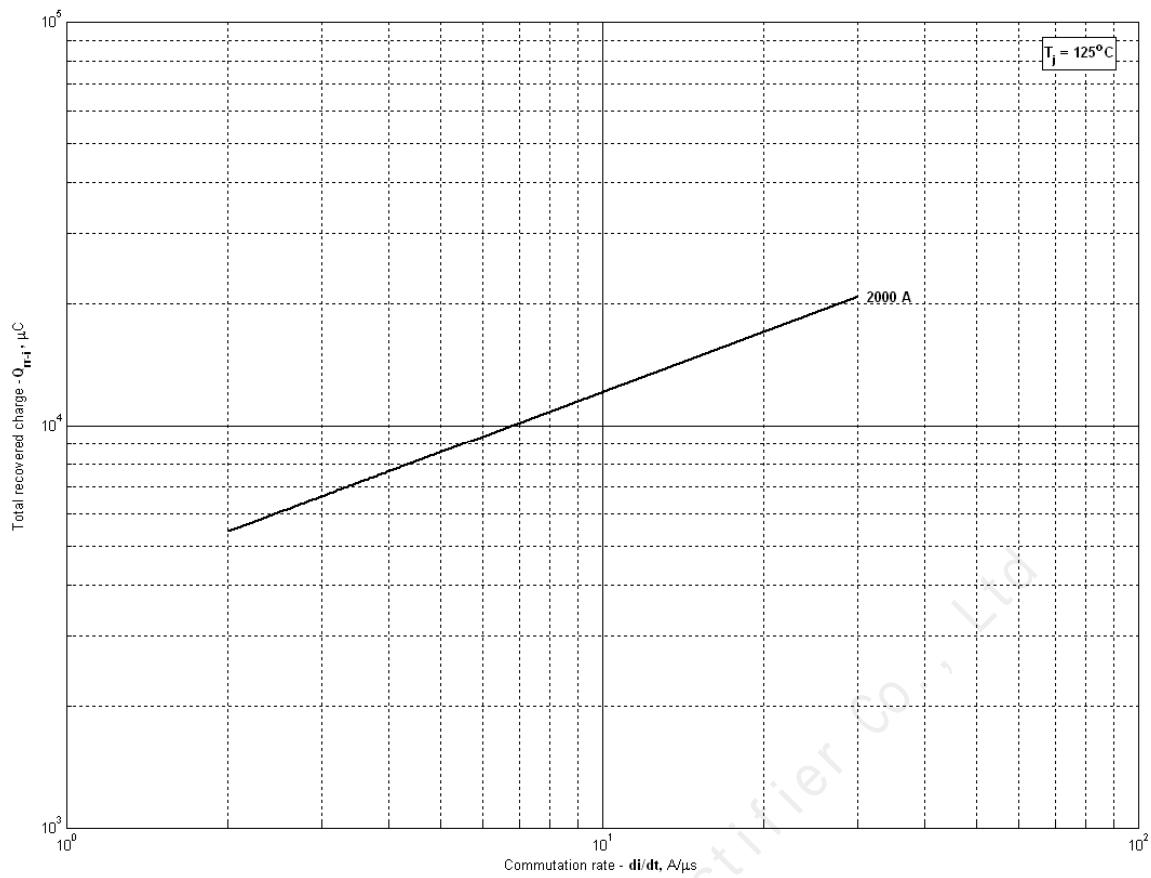


Fig 5 – Total recovered charge, Q_{rr-i} (integral)



Fig 6 - Recovered charge, Q_{rr} (linear)

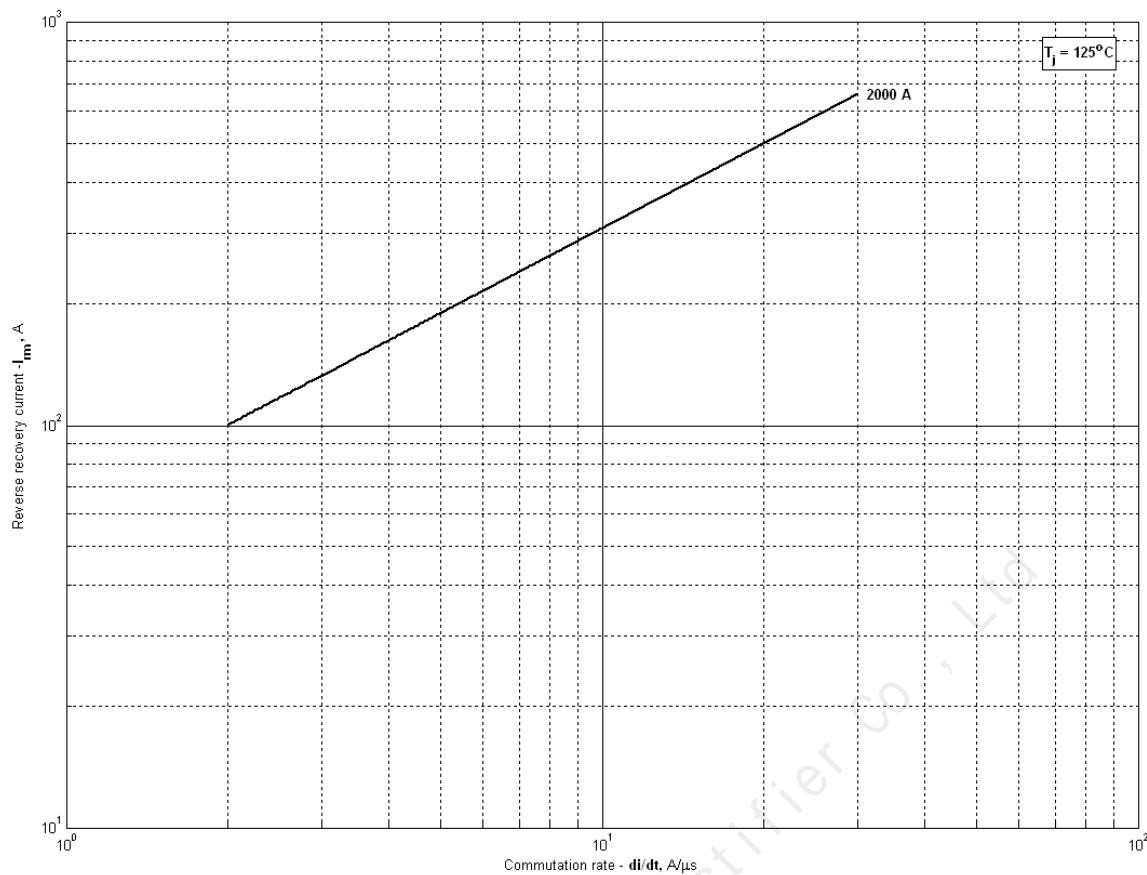


Fig 7 – Peak reverse recovery current, I_{rm}

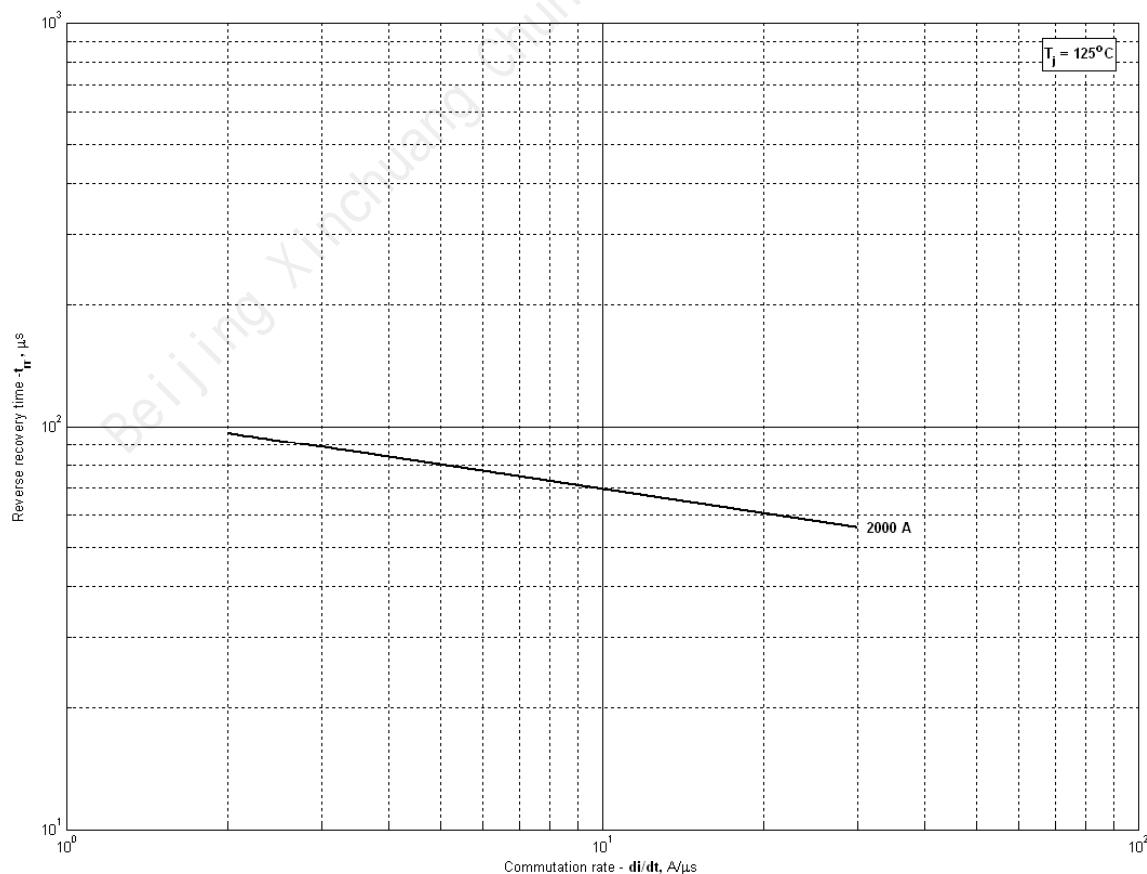


Fig 8 – Maximum recovery time, t_{rr} (linear)

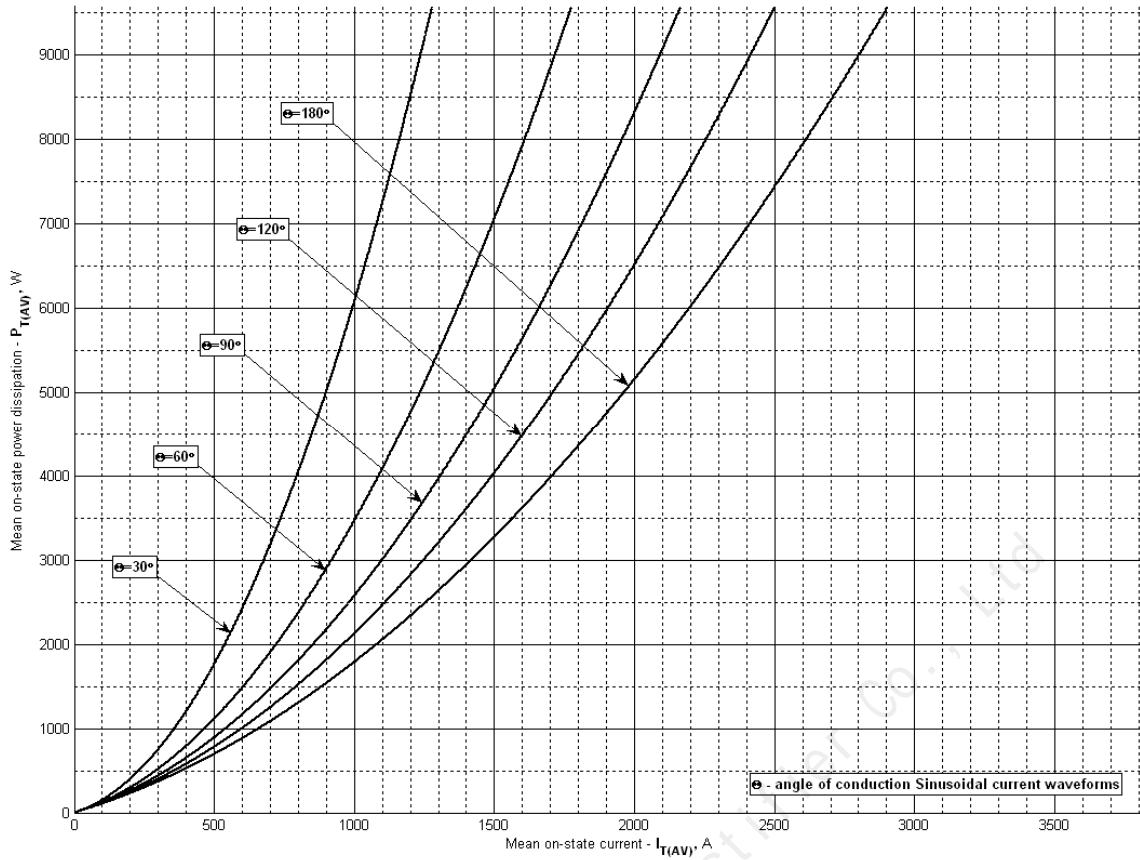


Fig 9 – On-state power loss (sinusoidal current waveforms)

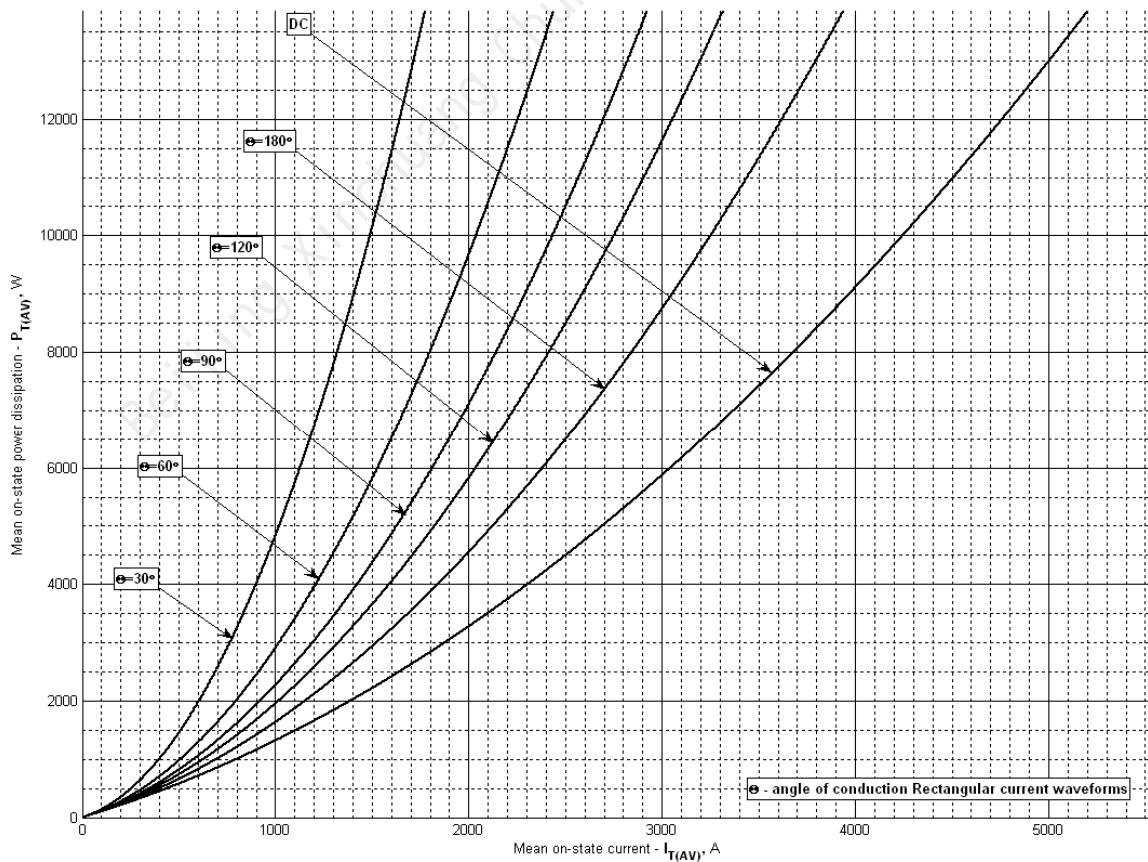


Fig 10 – On-state power loss (rectangular current waveforms)

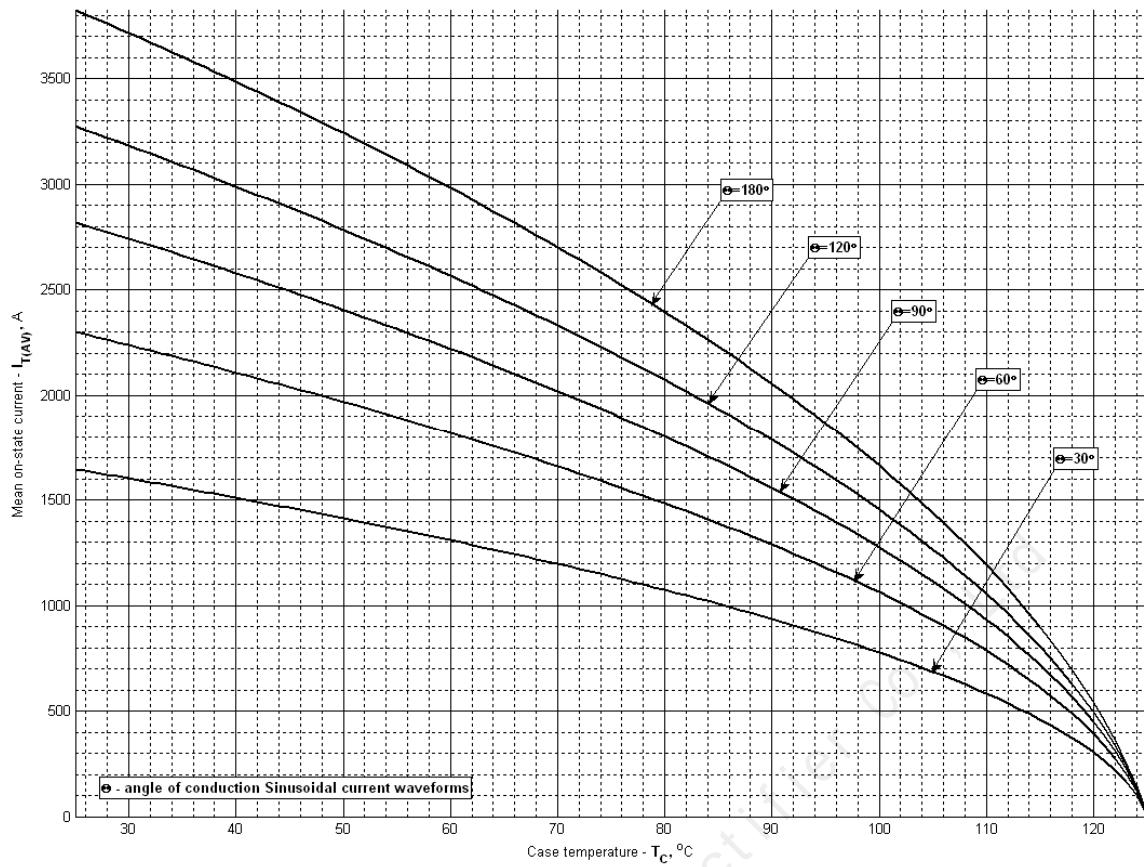


Fig 11 – Maximum case temperature DSC (sinusoidal current waveforms)

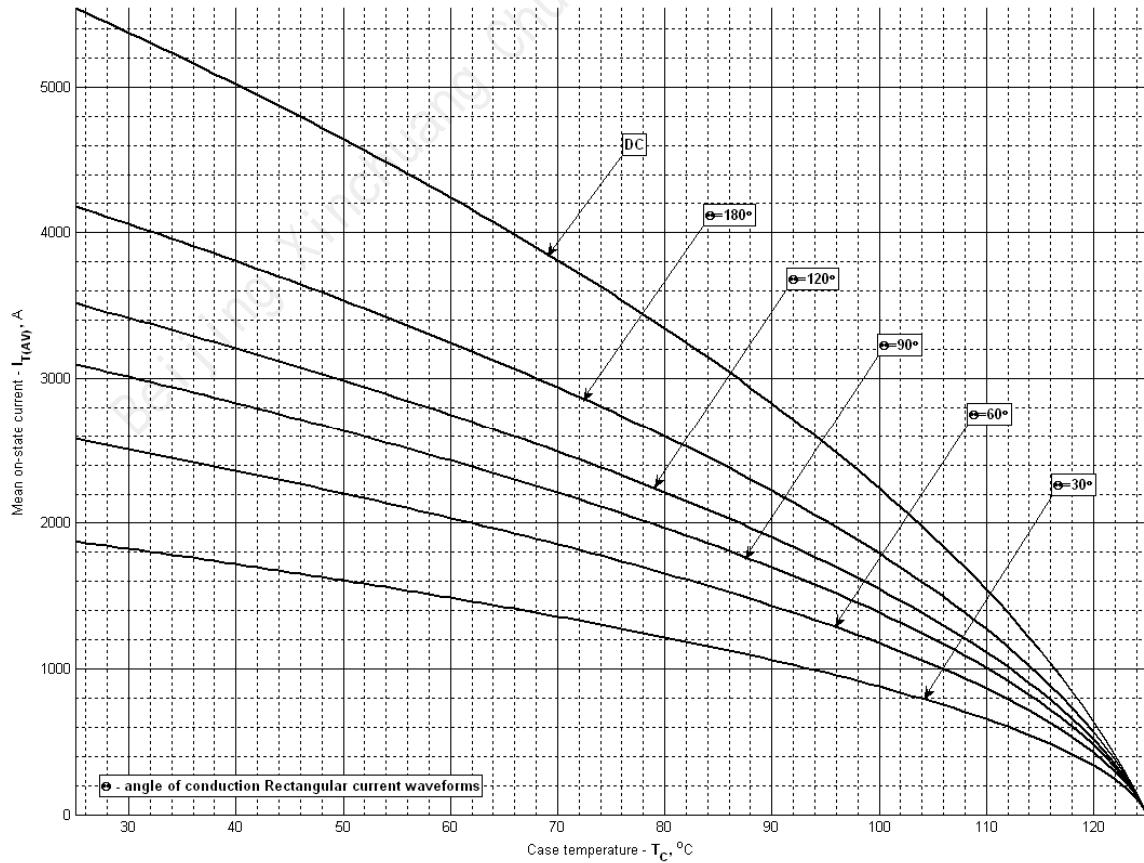


Fig 12 – Maximum case temperature DSC (rectangular current waveforms)

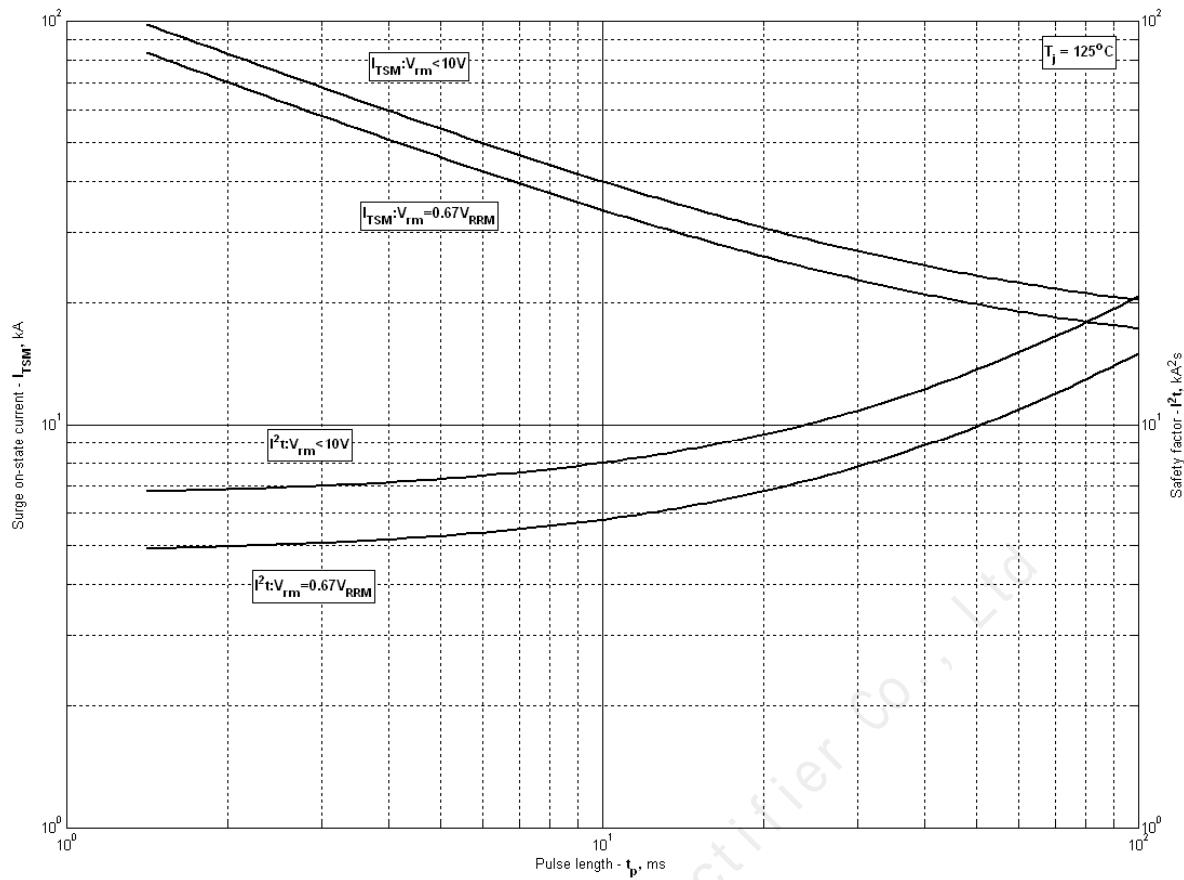


Fig 13 – Maximum surge and I^2t ratings

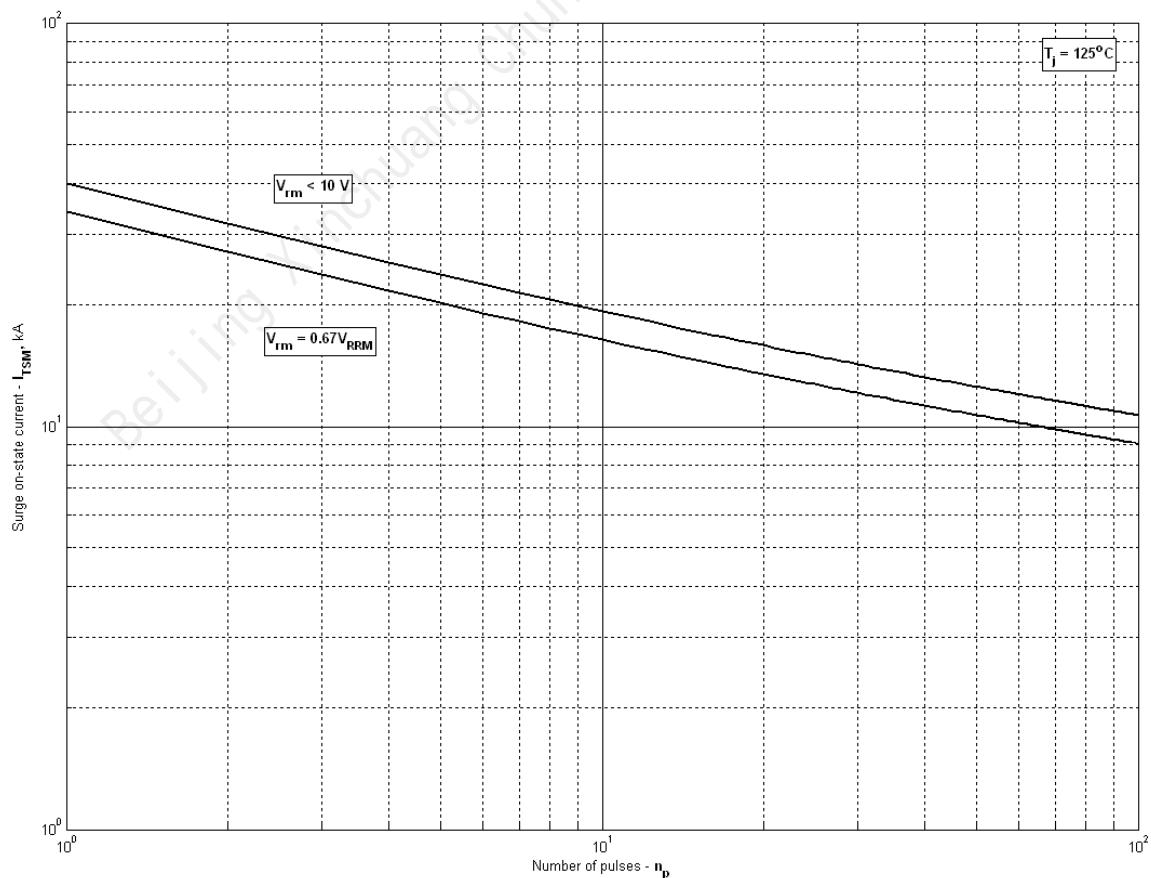


Fig 14 – Maximum surge ratings